ASSOCIATION CONNECTED ELECTRONICS INDUST	© Copyright 2005, IPC.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					Materia	ls and Mf	g Inforn	nation	
upplier Info	rmation														
Company name*		Company uni	Company unique ID			Unique ID Authority					Response Date*				
nsemi												2025-07-05			
Contact Name			Title - Contact			F	Phone - Contact*					Email - Contact*			
Product-Env-Ste	ewards	Product Enviro Compliance			]	NA					Product-Env-Stewards@onsemi.com				
Authorized Representative* Tit				Title - Representative			Phone - Representative*					Email - Representative*			
Product-Env-Ste	ewards	Product Enviro Compliance			1	NA					Product-Env-Stewards@onsemi.com				
Reque	ester Item Number	Mfr Item	em Number Mfr Item Name				Effective Da	te Version	rsion Manufacturing Site		Site	Weight*		UOM	Unit Type
		NCV8160AMX290TB XDFN4 AD 2.9V G Noise and High I				ra-Low	2025-07-05	ТНВ				1.29 mg		Each	
<b>Ianufacturin</b>	ng Proccess Information	1													
Termin	ninal Plating / Grid Array Material		Terminal Base Alloy J		J-STD-020 MSL Rating		Peak Process Body Ten		Гетрегаtur	erature Max Time at Peak		Temperature Number of Reflow Cycles		Cycles	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		1) (no C	CU Alloy 1		1		260		С	30	seco		s <b>3</b>		
Comments															
vel 1 - maximur	n time at peak temperature d	luring sol	dering is 10-3	0 seconds		·	·				·	·			
or more inform	ation regarding material com	position	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.106	mg	Supplier	Silicon (Si)	7440-21-3		0.106	mg
Die Attach Tape	0.01	mg	Supplier	Oxirane, (chloromethyl)-, homopolymer	24969-06-0		0.0015	mg
			Supplier	2-Propenoic acid, 2-methyl-, polymer with butyl 2-propenoate and methyl 2-methyl-2-propenoate	25035-69-2		0.0015	mg
			Supplier	Proprietary	Proprietary Data		0.001	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0045	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0015	mg
Lead Frame	0.78	mg	Supplier	Magnesium (Mg)	7439-95-4		0.0012	mg
			Supplier	Silicon (Si)	7440-21-3		0.0034	mg
			В	Nickel (Ni)	7440-02-0		0.0196	mg
			Supplier	Copper (Cu)	7440-50-8		0.7558	mg
Mold Compound-Black	0.35	mg		Epoxy resin	proprietary data		0.0164	mg
			Supplier	Phenol Resin	Proprietary Data		0.0164	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0004	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.3167	mg
Plating	0.024	mg	Supplier	Palladium (Pd)	7440-05-3		0.0006	mg
			В	Nickel (Ni)	7440-02-0		0.0211	mg
			Supplier	Gold (Au)	7440-57-5		0.0023	mg
Wire Bond - Au	0.02	mg	Supplier	Gold (Au)	7440-57-5		0.02	mg